FORM PTO-1595 (Rev. 6-93) OMB No. 0651-0011 (exp. 4/94)

ET

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office Attorney Docket No. 400.055US01

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  Donald M. Morgan  12-18-00	2. Name and address of receiving party(ies):  Name: Micron Technology, Inc.
Additional name(s) of conveying party(ies) attached?Yes _X_No  3. Nature of conveyance:	Street Address: 8000 South Federal Way
X Assignment Merger _ Security Agreement Change of Name _ Other  Execution Date: November 14, 2000	City: <u>Boise</u> State: <u>ID</u> ZIP: <u>83716</u> Additional name(s) & address(es) attached?YesX No
4. Application number(s) or patent number(s):	
The filing date of the application was August 30, 2000.	
A. Patent Application No(s).	B. Patent No(s).
09/651,639	
Title: BI-STATE FERROELECTRIC MEMORY D	EVICES, USES AND OPERATION
Additional numbers attached?Yes _X_No	
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
Name: Russell D. Slifer Address: Fogg Slifer & Polglaze, P.A. P.O. Box 581009 Minneapolis, MN 55458-1009	<ul> <li>7. Total fee (37 CFR §3.41): \$ 40.00</li> <li>X Enclosed Authorized to be charged to deposit account</li> <li>8. Please charge any additional fees or credit any overpayments to Deposit account number: 501373</li> </ul>
DO NOT USE THIS SPACE	
O. Statement and signature.  To the best of my knowledge and belief, the foregoing information copy of the original document.  Russell D. Slifer/Reg. No. 39,838  Name of Person Signing  Signature	on is true and correct and any attached copy is an original or a true  12//3/00  Date
Total number of pages including cover sheet, attachments, and document(s): 3	
Mail documents to be recorded with required cover sheet information to:  Commissioner of Patents  Box Assignments  Washington, D.C. 20231	

PATENT REEL: 011385 FRAME: 0718

## ASSIGNMENT

WHEREAS, I, Donald M. Morgan, residing at 5108 Chaps Place, Boise, Idaho, 83709, made certain new and useful inventions and improvements for which an application for Letters Patent of the United States was filed on <u>August 30, 2000</u>, and received U. S. Patent No. <u>09/651,639</u>, and which is entitled **MID-ARRAY ISOLATE CIRCUIT LAYOUT.** 

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, Boise, ID 83716-9632, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I do hereby agree that I and my executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore I covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me and that full right to convey the same as herein expressed is possessed by me.

PATENT REEL: 011385 FRAME: 0719 Docket No.: 400.050US01 Serial No.: 09/651,639 Title: MID-ARRAY ISOLATE CIRCUIT LAYER

**RECORDED: 12/18/2000** 

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